Product End-of-Life Disassembly Instructions

Product Category: Data Storage Devices
Marketing Name / Model [List multiple models if applicable.]
Ultrium 4, LTO1840 full height array module / EH856A
Ultrium 3, LTO960 full height array module / Q1540A
Ultrium 2, LTO460 full height array module / Q1512C

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx screwdriver	T5, T8 & T10

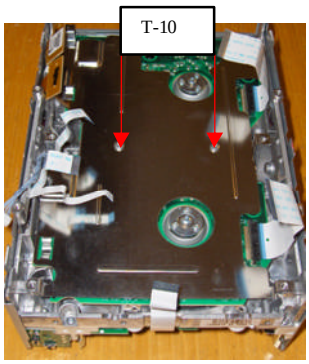
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

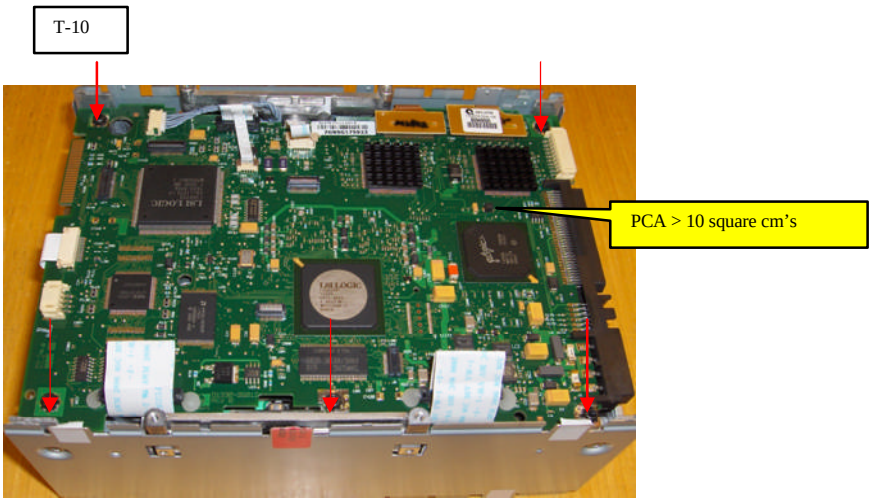
3.1.1 Remove the mechanism from the carrier. Secured by 4 x T-10 screws.
3.1.2 Remove the SCSI I/O PCA (> 10 square cm's) from the carrier assembly.
3.1.3 Mechanism disassembly: remove the front panel (clip fit – two clips top, two bottom), and remove the lid and the base. You will need to cut the 4 x tamper-proof tapes, top and bottom to clip off the lid and the base.
3.1.4 Remove the main PCA. Disconnect all FFC / FPC connectors and 1 x cable connector The main PCA is > 10 square cm's. See image 1. When the PCA is removed, remove the PCA shield - located underneath the main PCA and secured by 2 x T-10 screws – see image 1.
3.1.5 Remove the CMWP PCA. Slide the cartridge assembly 2 cm back into the mechanism. Remove 5 x T-5 screws securing the PCA and remove from the mechanism. PCA is > 10 square cm's – see image 2.
3.1.6 Remove the 2 x reel motor PCAs. Remove the tape reel. 3 x T-10 screws and cut the tape. Once removed, remove 3 x T-8 screws securing the front reel motor PCA and 3 x T-8 screws securing the rear reel motor PCA. Both reel motor PCAs are > 10 square cm's. See image 3.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1) **Main PCA and FFC connectors.**

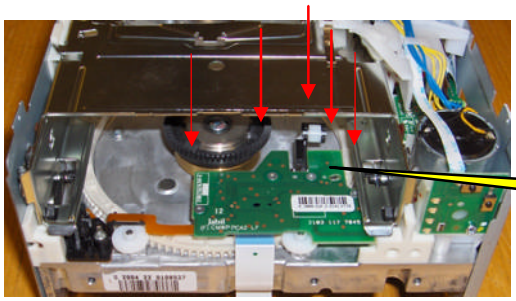


Above: PCA shield



2) **CMWP PCA.**

5 x T-5 screws



3) **Reel motor PCAs.**